

Method for forming metallic conductor patterns on electrically insulating substrates.

In order to form metallic conductor patterns having connection regions (CA1, LA1) that can be soldered and/or bonded on electrically insulating substrates (U1), firstly a metalization is applied to the substrate and is then removed again, at least in those regions adjoining the desired conductor pattern. There then follows the electrolytic deposition of a final surface (E) which can be soldered and/or bonded to the connection regions (CA1; LA1). Clean-room conditions are not necessary.

Figure 8